

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of

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**Applicants** 

Jigish D. Trivedi

Serial No.

08/915,658

Filed Title

August 21, 1997

LECHNOLOGA CENTER 5804. LOW RESISTANCE METAL SILICIDE LOCAL INTERCONNECTS

AND A METHOD OF MAKING

Docket No.

MIO 0024 PA

Examiner

G. Peralta

Art Unit

2814

Assistant Commissioner for Patents Washington, D.C. 20231

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on May 8, 2000.

James Eæeyer

Reg. No.

Sir:

## **RESPONSE**

This paper is being filed in response to the Office Action of February 10, 2000. Reconsideration of the present application is respectfully requested in light of the remarks below.

## **REMARKS**

Claims 31-40 are currently under consideration in the present application.

In the Office Action of February 10, 2000, claims 31-34 have been rejected under 35 U.S.C. § 102(b) as being anticipated by Okamoto (U.S. Patent 4,910,578). Claims 35-40 have been rejected under 35 U.S.C. § 103 (a) as being unpatentable over Okamoto in view of Shepard (U.S. Pat. 5,227,333).

Independent claim 31 recites a local interconnect comprising a first metal silicide, a second metal silicide, and an intermetallic compound comprising metal from said first metal silicide and metal from said second metal silicide. Independent claim 35 further